Data sheet Product ICK BGA 19 x 19 x 6



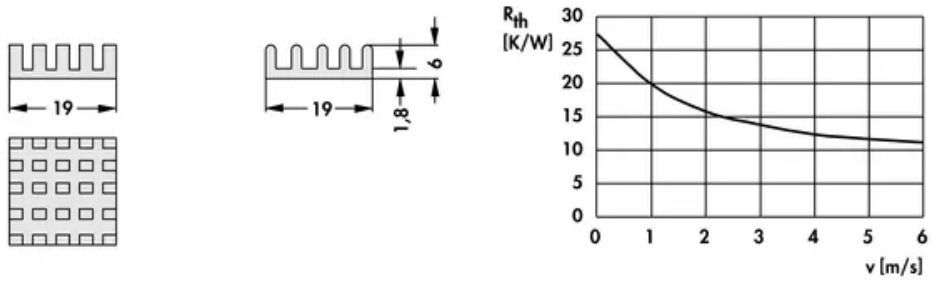
Heatsinks and active heatsinks for processors>Heatsinks for BGAs

19 x 19 x 6 mm, for IC design BGA and others

Features

way of fixation:	• **therm. conductive foil** • **therm. cond. adhesive**
socket:	**universal**
suitable for processor type:	**universal**
width:	**19 mm**
height:	**6 mm**
plate thickness:	**1.8 mm**
length:	**19 mm**
thermal resistance:	**27 - 11 K/W**
dissipation loss:	**2 W**
surface:	**black anodised**

Technical Drawing



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